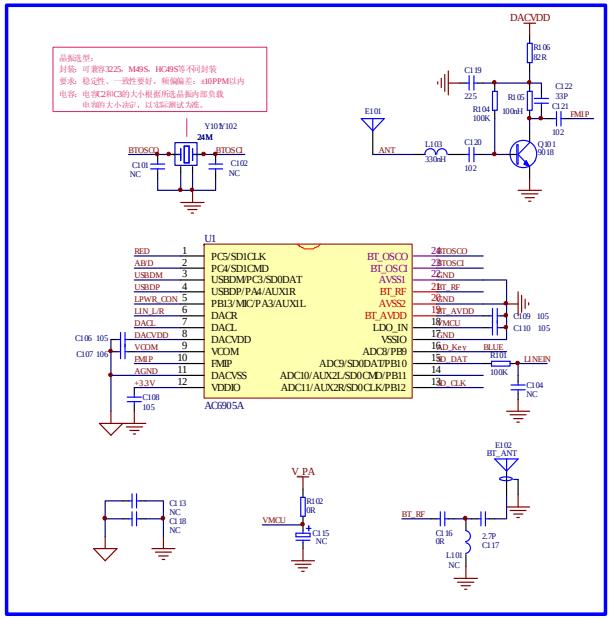
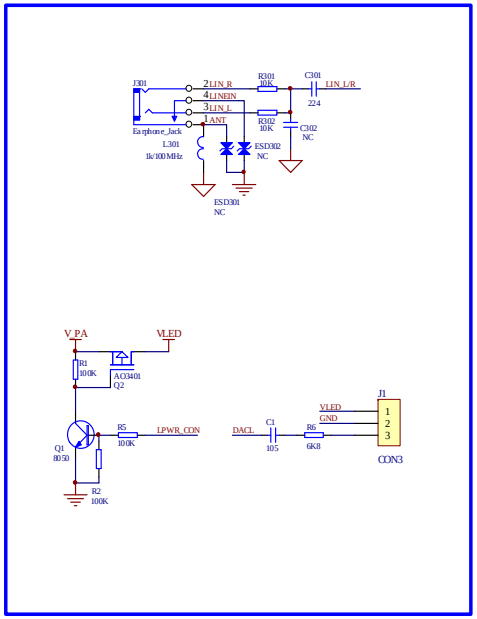
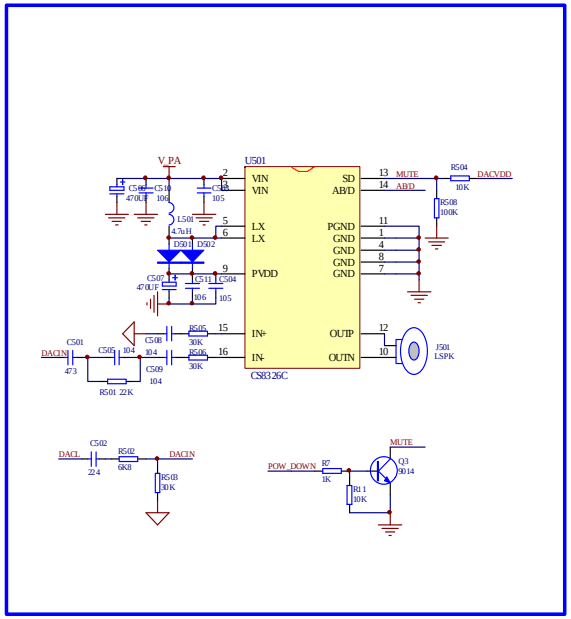
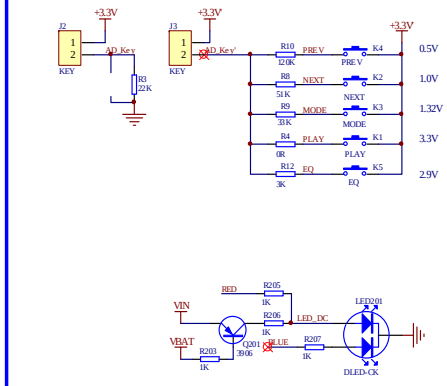
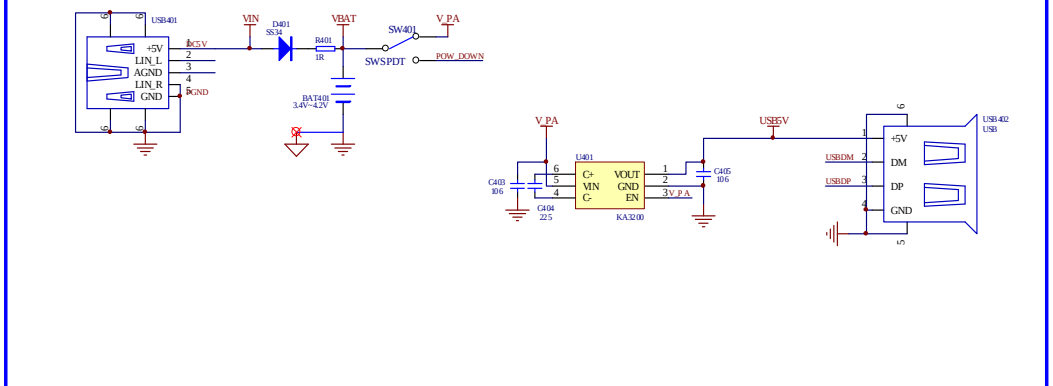

晶振选型：
封装：可兼容3225、M49S、HC49S等不同封装
要求：稳定性，一致性要好，频偏偏差：±10PPM以内
电容：电容C2和C3的大小根据所选晶振内部负载
电容的大小决定，以实际测试为准。
DACVDD
R106 2R
C119 22P
R105 100nH
C122 33P
C121 102
R104 100K
E101
ANT
L103 330nH
C120 102
Q101 9018
FMIP
Y101 24M
BTOSCO
BTOSCI
C101 NC
C102 NC
U1
RED 1
ABD 2
USBDM 3
USBDP 4
LPWR_CON 5
LIN_L/R 6
DACL 7
DACVDD 8
VCOM 9
FMIP 10
AGND 11
+3.3V 12
PC5/SD1CLK
PC4/SD1CMD
USBDM/PC2/SD0DAT
USBDP/PA4/AUX1R
PB13/MIC/PA3/AUX1L
DACR
DACL
DACVDD
VCOM
FMIP
DACVSS
VDDIO
BT_OSCO
BT_OSCI
AVSS1
BT_RF
AVSS2
BT_AVDD
LDO_IN
VSSIO
ADC8/PB9
ADC9/SD0DATPB10
ADC10/AUX2L/SD0CMD/PB11
ADC11/AUX2R/SD0CLK/PB12
24 BTOSCO
23 BTOSCI
22 GND
21 BT_RF
20 GND
19 BT_AVDD
18 VMCU
17 GND
16 AD_Key
15 SD_DAT
14
13 SD_CLK
BLUE
R101 100K
LINEIN
C104 NC
ACE6905A
C106 105
C107 106
C108 105
C109 105
C110 105
C113 NC
C118 NC
V_PA
R102 0R
VMCU
C115 NC
C116 0R
C117 2.7P
L101 NC
BT_RF
E102 BT_ANT


J301
Earphone_Jack
L301
1k/100 MHz
2 LIN_R
4 LINEIN
3 LIN_L
1 ANT
R301 10K
R302 10K
C301 224
LIN_L/R
C302 NC
ESD302 NC
ESD301 NC
V_PA
VLED
R1 100K
AO3401 Q2
Q1 8050
R5 100K
LPWR_CON
R2 100K
DACL
C1 105
R6 6K8
VLED
GND
J1
1
2
3
CON3


V_PA
U501
C506 470UF
C510 106
C512 105
L501 4.7uH
D501 D502
C507 470UF
C511 106
C504 105
PVDD
VIN
VIN
LX
LX
PGND
GND
GND
GND
SD
ABD
MUTE
ABD
R504 10K
DACVDD
R508 100K
C501 DACIN 473
C505 104
R501 22K
C508 104
C509 104
R505 30K
R506 30K
IN+
IN-
OUTP
OUTN
CS8326C
J501 LSPK
C502 DACL 224
R502 6K8
R503 10K
DACIN
POW_DOWN
R7 1K
R11 10K
Q3 9014
MUTE


+3.3V
J2
KEY
AD_Key
R3 22K
+3.3V
J3
KEY
AD_Key'
R10 120K
PREV
K4
R8 51K
NEXT
K2
R9 33K
MODE
K3
R4 0R
PLAY
K1
R12 3K
EQ
K5
+3.3V
0.5V
1.0V
1.32V
3.3V
2.9V

RED
R205 1K
VIN
R206 1K
LED_DC
LED201
VBAT
Q201 3906
BLUE
R207 1K
R203 1K
DLED-CK


USB401
+5V
LIN_L
AGND
LIN_R
GND
DGND
AGND
VIN
D401 SS34
R403 1R
VBAT
BAT401 3.4V~4.2V
SW401
SWSPDT
V_PA
POW_DOWN
V_PA
C403 106
U401
C+
VIN
C-
VOUT
GND
EN
KA3200
C404 225
3V_P.A
C405 106
USB5V
USB402 USB
+5V
DM
DP
GND
USBDM
USBDP